

USB3.1C S1H DN1 RL**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

**General ordering data**

Version	OMNIMATE Data - USB jack, USB jacks, 10 Gbit/s, SMD solder connection, 90°, ≥ 10000, Pitch in mm (P): 0.50 mm, Number of poles: 24, LCP, black, Reel
Order No.	2987560000
Type	USB3.1C S1H DN1 RL
GTIN (EAN)	4099986855052
Qty.	1,050 pc(s).
Packaging	Reel

Creation date July 5, 2024 1:12:56 AM CEST

Catalogue status 29.06.2024 / We reserve the right to make technical changes.

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Technical data

Dimensions and weights

Depth	7.9 mm	Depth (inches)	0.311 inch
Height	3.21 mm	Height (inches)	0.126 inch
Width	8.94 mm	Width (inches)	0.352 inch
Net weight	10 g		

System specifications

Mounting onto the PCB	SMD solder connection	Number of poles	24
Number of solder pins per pole	1	Outgoing elbow	90°
Performance-Category	10 Gbit/s	Pitch in inches (P)	0.02 "
Pitch in mm (P)	0.5 mm	Plugging cycles	≥ 10000
Product family	OMNIMATE Data - USB jack	Protection degree	IP20
Shield surface	nickel-plated	Shield tabs	none
Shielding	360° shield contact	Shielding material	Brass
Side termination, characteristic	None	Solder pin length (l)	1.15 mm
Soldering process	Reflow soldering, Manual soldering	Transmission rate	10 Gbit/s

Electrical properties

Dielectric strength, contact / contact	750 V AC	Insulation strength	≥ 100 MΩ
Rated voltage	5 V		

Material data

Insulating material	LCP	Colour	black
Colour chart (similar)	RAL 9011	Insulation strength	≥ 100 MΩ
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact base material	Copper alloy	Contact material	Gold over nickel
Contact surface	Gold over nickel	Operating temperature, min.	-40 °C
Operating temperature, max.	80 °C		

Packing

Packaging	Reel	VPE length	0
VPE width	0	VPE height	0

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01		

Environmental Product Compliance

REACH SVHC /

Approvals

ROHS Conform

Data sheet

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Technical data

Downloads

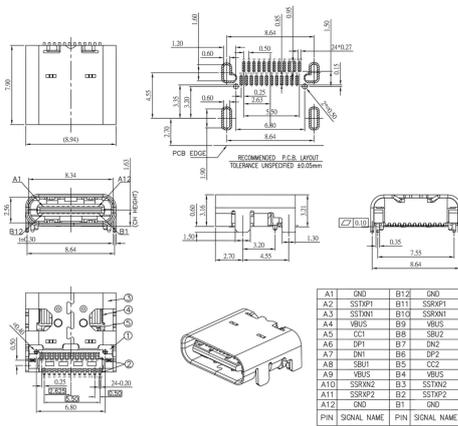
Engineering Data	CAD data – STEP
Catalogues	Catalogues in PDF-format

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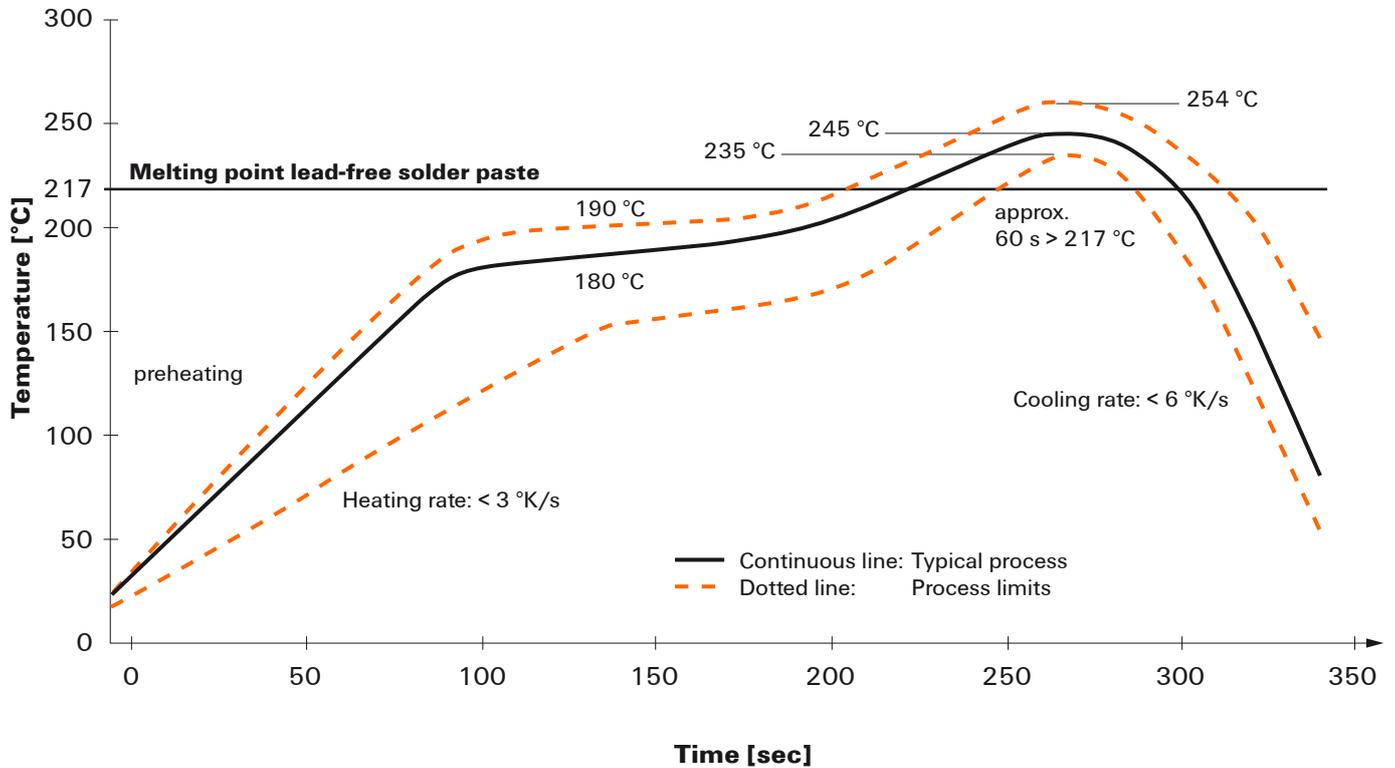
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Drawings



Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG
 Klingenbergstraße 16
 D-32758 Detmold
 Germany
 Fon: +49 5231 14-0
 Fax: +49 5231 14-292083
 www.weidmueller.com



Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is ‚activated‘. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.